



Material Declaration Sheet and ICP Analysis

Product Group: Vishay Siliconix

Part Number: SI4840BDY-T1-GE3

Package Type: SOIC-8 BWL

Package Total Mass (g): 0.09403

Component	Substance	CAS Number	Amount of Substance (g)	Percent (%)	PPM
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Semiconductor Device

Silicon Chip	Doped Silicon	7440-21-3	0.0103	10.79	107,892
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Lead Frame

Base Metal	Copper	7440-50-8	0.02907	30.96	309,617
Base Metal	Zinc	7440-66-6	0.00004	0.04	381
Base Metal	Phosphorous	7723-14-0	0.00001	0.01	95
Base Metal	Iron	7439-89-6	0.00069	0.73	7,300

Bond Wire

Metallurgy	Gold	7440-57-5	0.00001	0.01	107
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Clip

Base Metal	Chromium	7440-47-3	0.00002	0.02	207
Base Metal	Tin	7440-31-5	0.00002	0.02	216
Base Metal	Zinc	7440-66-6	0.00002	0.02	190
Base Metal	Copper	7440-50-8	0.00800	8.52	85,659

Die Attach Adhesive

Conductive Material	Tin	7440-31-5	0.00144	1.53	15,337
Polymer	Lead	7439-92-1	0.01056	11.25	112,472

Mold Compound

Epoxy	Epoxy Resin	29690-82-2	0.00265	2.82	28,246
Flame Retardant Additive	Phenol Resin	9003-35-4	0.00232	2.47	24,715
Filler	Fused Silica	60676-86-0	0.02553	27.19	271,866
Flame Retardant Polymer	Aluminum Hydroxide	21645-51-2	0.00265	2.82	28,246

Solder Plating

Plating	Tin	7440-31-5	0.00070	0.75	7,456
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Vishay Intertechnology, Inc.

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